



# Material Composition Declaration

## EPC2221

Company Name	Efficient Power Conversion (EPC)	Issue Date:	4/5/2022
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0280	Contact Email:	yanping.ma@epc-co.com
Part Weight:	2.5 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	2.1125	85.3530	88.3008	853530
	Silicon oxide	7631-86-9	0.0101	0.4079		4079
	Silicon nitride	12033-89-5	0.0032	0.1299		1299
	Gallium nitride	25617-97-4	0.0134	0.5434		5434
	Aluminum	7429-90-5	0.0212	0.8570		8570
	Aluminum nitride	24304-00-5	0.0033	0.1322		1322
	Titanium	7440-32-6	0.0003	0.0117		117
	Titanium nitride	25583-20-4	0.0007	0.0298		298
	Copper	7440-50-8	0.0004	0.0143		143
	Tungsten	7440-33-7	0.0006	0.0241		241
	Polyimide		0.0197	0.7976	7976	
Under Bump Metal	Titanium	7440-32-6	0.0002	0.0082	0.0893	82
	Copper	7440-50-8	0.0020	0.0812		812
Solder Bump	Copper	7440-50-8	0.0201	0.8117	11.6099	8117
	Nickel	7440-02-0	0.0120	0.4842		4842
	Tin	7440-31-5	0.2507	10.1283		101283
	Silver	7440-22-4	0.0046	0.1857		1857
Sum in total:			2.4750	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.